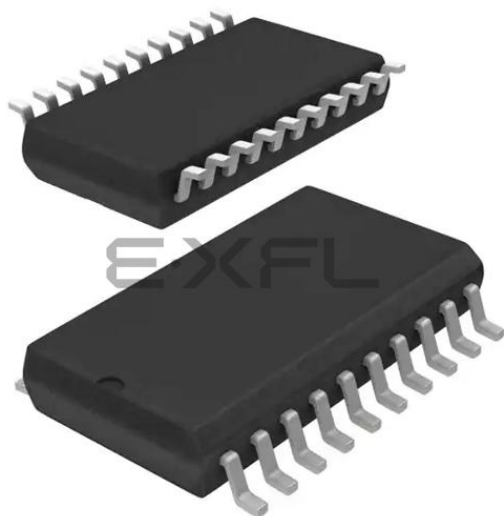




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Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LED, LVD, POR, PWM
Number of I/O	15
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.3V
Data Converters	A/D 12x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc68hc908jk3cdw

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1.6 Pin Functions

Description of the pin functions are provided in [Table 1-2](#).

Table 1-2. Pin Functions

PIN NAME	PIN DESCRIPTION	IN/OUT	VOLTAGE LEVEL
VDD	Power supply.	In	5V or 3V
VSS	Power supply ground	Out	0V
$\overline{\text{RST}}$	RESET input, active low. With Internal pull-up and schmitt trigger input.	Input	VDD
$\overline{\text{IRQ1}}$	External IRQ pin. With software programmable internal pull-up and schmitt trigger input. This pin is also used for mode entry selection.	Input	VDD to VDD+V _{HI}
OSC1	X-tal or RC oscillator input.	In	Analog
OSC2	For X-tal oscillator option: X-tal oscillator output, this is the inverting OSC1 signal.	Out	Analog
	For RC oscillator option: Default is RCCLK output. Shared with PTA6/KBI6, with programmable pull-up.	In/Out	VDD
PTA[0:6]	7-bit general purpose I/O port.	In/Out	VDD
	Shared with 7 keyboard interrupts KBI[0:6].	In	VDD
	Each pin has programmable internal pull-up device.	In	VDD
PTB[0:7]	8-bit general purpose I/O port.	In/Out	VDD
	Shared with 8 ADC inputs, ADC[0:7].	In	Analog
PTD[0:7]	8-bit general purpose I/O port.	In/Out	VDD
	PTD[3:0] shared with 4 ADC inputs, ADC[8:11].	Input	Analog
	PTD[4:5] shared with TIM channels, TCH0 and TCH1.	In/Out	VDD
	PTD[6:7] can be configured as 25mA open-drain output with pull-up.	In/Out	VDD

NOTE: On the 20-pin package, the following pins are not available:
PTA0, PTA1, PTA2, PTA3, PTA4, PTA5, PTD0, and PTD1.

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$0000	Port A Data Register (PTA)	Read:	0	PTA6	PTA5	PTA4	PTA3	PTA2	PTA1	PTA0
		Write:								
		Reset:	Unaffected by reset							
\$0001	Port B Data Register (PTB)	Read:	PTB7	PTB6	PTB5	PTB4	PTB3	PTB2	PTB1	PTB0
		Write:								
		Reset:	Unaffected by reset							
\$0002	Unimplemented	Read:								
		Write:								
\$0003	Port D Data Register (PTD)	Read:	PTD7	PTD6	PTD5	PTD4	PTD3	PTD2	PTD1	PTD0
		Write:								
		Reset:	Unaffected by reset							
\$0004	Data Direction Register A (DDRA)	Read:	0	DDRA6	DDRA5	DDRA4	DDRA3	DDRA2	DDRA1	DDRA0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$0005	Data Direction Register B (DDRB)	Read:	DDRB7	DDRB6	DDRB5	DDRB4	DDRB3	DDRB2	DDRB1	DDRB0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$0006	Unimplemented	Read:								
		Write:								
\$0007	Data Direction Register D (DDRD)	Read:	DDRD7	DDRD6	DDRD5	DDRD4	DDRD3	DDRD2	DDRD1	DDRD0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$0008 ↓ \$0009	Unimplemented	Read:								
\$000A	Port D Control Register (PDCR)	Read:	0	0	0	0	SLOWD7	SLOWD6	PTDPU7	PTDPU6
		Write:								
		Reset:	0	0	0	0	0	0	0	0
				= Unimplemented			R	= Reserved		

Figure 2-2. Control, Status, and Data Registers (Sheet 1 of 5)

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$0021	TIM Counter Register High (TCNTH)	Read:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$0022	TIM Counter Register Low (TCNTL)	Read:	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$0023	TIM Counter Modulo Register High (TMODH)	Read:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
		Write:								
		Reset:	1	1	1	1	1	1	1	1
\$0024	TIM Counter Modulo Register Low (TMDL)	Read:	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
		Write:								
		Reset:	1	1	1	1	1	1	1	1
\$0025	TIM Channel 0 Status and Control Register (TSC0)	Read:	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	TOV0	CH0MAX
		Write:	0							
		Reset:	0	0	0	0	0	0	0	0
\$0026	TIM Channel 0 Register High (TCH0H)	Read:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
		Write:								
		Reset:	Indeterminate after reset							
\$0027	TIM Channel 0 Register Low (TCH0L)	Read:	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
		Write:								
		Reset:	Indeterminate after reset							
\$0028	TIM Channel 1 Status and Control Register (TSC1)	Read:	CH1F	CH1IE	0	MS1A	ELS1B	ELS1A	TOV1	CH1MAX
		Write:	0							
		Reset:	0	0	0	0	0	0	0	0
\$0029	TIM Channel 1 Register High (TCH1H)	Read:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
		Write:								
		Reset:	Indeterminate after reset							
\$002A	TIM Channel 1 Register Low (TCH1L)	Read:	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
		Write:								
		Reset:	Indeterminate after reset							

= Unimplemented
 = Reserved

Figure 2-2. Control, Status, and Data Registers (Sheet 3 of 5)



6.6.2 Stop Mode

The STOP instruction:

- Clears the interrupt mask (I bit) in the condition code register, enabling external interrupts. After exit from stop mode by external interrupt, the I bit remains clear. After exit by reset, the I bit is set.
- Disables the CPU clock

After exiting stop mode, the CPU clock begins running after the oscillator stabilization delay.

6.7 CPU During Break Interrupts

If a break module is present on the MCU, the CPU starts a break interrupt by:

- Loading the instruction register with the SWI instruction
- Loading the program counter with \$FFFC:\$FFFD or with \$FEFC:\$FEFD in monitor mode

The break interrupt begins after completion of the CPU instruction in progress. If the break address register match occurs on the last cycle of a CPU instruction, the break interrupt begins immediately.

A return-from-interrupt instruction (RTI) in the break routine ends the break interrupt and returns the MCU to normal operation if the break interrupt has been deasserted.

6.8 Instruction Set Summary

6.9 Opcode Map

See [Table 6-2](#).

Table 6-1. Instruction Set Summary

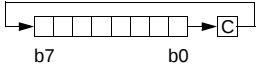
Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z	C				
ROR <i>opr</i> RORA RORX ROR <i>opr</i> ,X ROR ,X ROR <i>opr</i> ,SP	Rotate Right through Carry		↑	–	–	↑	↑	↑	DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	dd ff ff	4 1 1 4 3 5
RSP	Reset Stack Pointer	SP ← \$FF	–	–	–	–	–	–	INH	9C		1
RTI	Return from Interrupt	SP ← (SP) + 1; Pull (CCR) SP ← (SP) + 1; Pull (A) SP ← (SP) + 1; Pull (X) SP ← (SP) + 1; Pull (PCH) SP ← (SP) + 1; Pull (PCL)	↑	↑	↑	↑	↑	↑	INH	80		7
RTS	Return from Subroutine	SP ← SP + 1; Pull (PCH) SP ← SP + 1; Pull (PCL)	–	–	–	–	–	–	INH	81		4
SBC # <i>opr</i> SBC <i>opr</i> SBC <i>opr</i> SBC <i>opr</i> ,X SBC <i>opr</i> ,X SBC ,X SBC <i>opr</i> ,SP SBC <i>opr</i> ,SP	Subtract with Carry	A ← (A) – (M) – (C)	↑	–	–	↑	↑	↑	IMM DIR EXT IX2 IX1 IX SP1 SP2	A2 B2 C2 D2 E2 F2 9EE2 9ED2	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
SEC	Set Carry Bit	C ← 1	–	–	–	–	–	1	INH	99		1
SEI	Set Interrupt Mask	I ← 1	–	–	1	–	–	–	INH	9B		2
STA <i>opr</i> STA <i>opr</i> STA <i>opr</i> ,X STA <i>opr</i> ,X STA ,X STA <i>opr</i> ,SP STA <i>opr</i> ,SP	Store A in M	M ← (A)	0	–	–	↑	↑	–	DIR EXT IX2 IX1 IX SP1 SP2	B7 C7 D7 E7 F7 9EE7 9ED7	dd hh ll ee ff ff ff ff ee ff	3 4 4 3 2 4 5
STHX <i>opr</i>	Store H:X in M	(M:M + 1) ← (H:X)	0	–	–	↑	↑	–	DIR	35	dd	4
STOP	Enable $\overline{\text{IRQ}}$ Pin; Stop Oscillator	I ← 0; Stop Oscillator	–	–	0	–	–	–	INH	8E		1
STX <i>opr</i> STX <i>opr</i> STX <i>opr</i> ,X STX <i>opr</i> ,X STX ,X STX <i>opr</i> ,SP STX <i>opr</i> ,SP	Store X in M	M ← (X)	0	–	–	↑	↑	–	DIR EXT IX2 IX1 IX SP1 SP2	BF CF DF EF FF 9EEF 9EDF	dd hh ll ee ff ff ff ff ee ff	3 4 4 3 2 4 5

Table 6-2. Opcode Map

	Bit Manipulation		Branch	Read-Modify-Write						Control		Register/Memory							
	DIR	DIR	REL	DIR	INH	INH	IX1	SP1	IX	INH	INH	IMM	DIR	EXT	IX2	SP2	IX1	SP1	IX
MSB LSB	0	1	2	3	4	5	6	9E6	7	8	9	A	B	C	D	9ED	E	9EE	F
0	BRSET0 3 DIR	BSET0 2 DIR	BRA 2 REL	NEG 2 DIR	NEGA 1 INH	NEGX 1 INH	NEG 2 IX1	NEG 3 SP1	NEG 1 IX	RTI 1 INH	BGE 2 REL	SUB 2 IMM	SUB 2 DIR	SUB 3 EXT	SUB 3 IX2	SUB 4 SP2	SUB 2 IX1	SUB 3 SP1	SUB 1 IX
1	BRCLR0 3 DIR	BCLR0 2 DIR	BRN 2 REL	CBEQ 3 DIR	CBEQA 3 IMM	CBEQX 3 IMM	CBEQ 3 IX1+	CBEQ 4 SP1	CBEQ 2 IX+	RTS 1 INH	BLT 2 REL	CMP 2 IMM	CMP 2 DIR	CMP 3 EXT	CMP 3 IX2	CMP 4 SP2	CMP 2 IX1	CMP 3 SP1	CMP 1 IX
2	BRSET1 3 DIR	BSET1 2 DIR	BHI 2 REL		MUL 1 INH	DIV 1 INH	NSA 1 INH		DAA 1 INH		BGT 2 REL	SBC 2 IMM	SBC 2 DIR	SBC 3 EXT	SBC 3 IX2	SBC 4 SP2	SBC 2 IX1	SBC 3 SP1	SBC 1 IX
3	BRCLR1 3 DIR	BCLR1 2 DIR	BLS 2 REL	COM 2 DIR	COMA 1 INH	COMX 1 INH	COM 2 IX1	COM 3 SP1	COM 1 IX	SWI 1 INH	BLE 2 REL	CPX 2 IMM	CPX 2 DIR	CPX 3 EXT	CPX 3 IX2	CPX 4 SP2	CPX 2 IX1	CPX 3 SP1	CPX 1 IX
4	BRSET2 3 DIR	BSET2 2 DIR	BCC 2 REL	LSR 2 DIR	LSRA 1 INH	LSRX 1 INH	LSR 2 IX1	LSR 3 SP1	LSR 1 IX	TAP 1 INH	TXS 1 INH	AND 2 IMM	AND 2 DIR	AND 3 EXT	AND 3 IX2	AND 4 SP2	AND 2 IX1	AND 3 SP1	AND 1 IX
5	BRCLR2 3 DIR	BCLR2 2 DIR	BCS 2 REL	STHX 2 DIR	LDHX 3 IMM	LDHX 2 DIR	CPHX 3 IMM		CPHX 2 DIR	TPA 1 INH	TSX 1 INH	BIT 2 IMM	BIT 2 DIR	BIT 3 EXT	BIT 3 IX2	BIT 4 SP2	BIT 2 IX1	BIT 3 SP1	BIT 1 IX
6	BRSET3 3 DIR	BSET3 2 DIR	BNE 2 REL	ROR 2 DIR	RORA 1 INH	RORX 1 INH	ROR 2 IX1	ROR 3 SP1	ROR 1 IX	PULA 1 INH		LDA 2 IMM	LDA 2 DIR	LDA 3 EXT	LDA 3 IX2	LDA 4 SP2	LDA 2 IX1	LDA 3 SP1	LDA 1 IX
7	BRCLR3 3 DIR	BCLR3 2 DIR	BEQ 2 REL	ASR 2 DIR	ASRA 1 INH	ASRX 1 INH	ASR 2 IX1	ASR 3 SP1	ASR 1 IX	PSHA 1 INH	TAX 1 INH	AIS 2 IMM	STA 2 DIR	STA 3 EXT	STA 3 IX2	STA 4 SP2	STA 2 IX1	STA 3 SP1	STA 1 IX
8	BRSET4 3 DIR	BSET4 2 DIR	BHCC 2 REL	LSL 2 DIR	LSLA 1 INH	LSLX 1 INH	LSL 2 IX1	LSL 3 SP1	LSL 1 IX	PULX 1 INH	CLC 1 INH	EOR 2 IMM	EOR 2 DIR	EOR 3 EXT	EOR 3 IX2	EOR 4 SP2	EOR 2 IX1	EOR 3 SP1	EOR 1 IX
9	BRCLR4 3 DIR	BCLR4 2 DIR	BHCS 2 REL	ROL 2 DIR	ROLA 1 INH	ROLX 1 INH	ROL 2 IX1	ROL 3 SP1	ROL 1 IX	PSHX 1 INH	SEC 1 INH	ADC 2 IMM	ADC 2 DIR	ADC 3 EXT	ADC 3 IX2	ADC 4 SP2	ADC 2 IX1	ADC 3 SP1	ADC 1 IX
A	BRSET5 3 DIR	BSET5 2 DIR	BPL 2 REL	DEC 2 DIR	DECA 1 INH	DECX 1 INH	DEC 2 IX1	DEC 3 SP1	DEC 1 IX	PULH 1 INH	CLI 1 INH	ORA 2 IMM	ORA 2 DIR	ORA 3 EXT	ORA 3 IX2	ORA 4 SP2	ORA 2 IX1	ORA 3 SP1	ORA 1 IX
B	BRCLR5 3 DIR	BCLR5 2 DIR	BMI 2 REL	DBNZ 3 DIR	DBNZA 2 INH	DBNZX 2 INH	DBNZ 3 IX1	DBNZ 4 SP1	DBNZ 2 IX	PSHH 1 INH	SEI 1 INH	ADD 2 IMM	ADD 2 DIR	ADD 3 EXT	ADD 3 IX2	ADD 4 SP2	ADD 2 IX1	ADD 3 SP1	ADD 1 IX
C	BRSET6 3 DIR	BSET6 2 DIR	BMC 2 REL	INC 2 DIR	INCA 1 INH	INCX 1 INH	INC 2 IX1	INC 3 SP1	INC 1 IX	CLRH 1 INH	RSP 1 INH		JMP 2 DIR	JMP 3 EXT	JMP 3 IX2		JMP 2 IX1		JMP 1 IX
D	BRCLR6 3 DIR	BCLR6 2 DIR	BMS 2 REL	TST 2 DIR	TSTA 1 INH	TSTX 1 INH	TST 2 IX1	TST 3 SP1	TST 1 IX		NOP 1 INH	BSR 2 REL	JSR 2 DIR	JSR 3 EXT	JSR 3 IX2		JSR 2 IX1		JSR 1 IX
E	BRSET7 3 DIR	BSET7 2 DIR	BIL 2 REL		MOV 3 DD	MOV 2 DIX+	MOV 3 IMD		MOV 2 IX+D	STOP 1 INH	*	LDX 2 IMM	LDX 2 DIR	LDX 3 EXT	LDX 3 IX2	LDX 4 SP2	LDX 2 IX1	LDX 3 SP1	LDX 1 IX
F	BRCLR7 3 DIR	BCLR7 2 DIR	BIH 2 REL	CLR 2 DIR	CLRA 1 INH	CLR 1 INH	CLR 2 IX1	CLR 3 SP1	CLR 1 IX	WAIT 1 INH	TXA 1 INH	AIX 2 IMM	STX 2 DIR	STX 3 EXT	STX 3 IX2	STX 4 SP2	STX 2 IX1	STX 3 SP1	STX 1 IX

INH Inherent
IMM Immediate
DIR Direct
EXT Extended
DD Direct-Direct
IX+D Indexed-Direct

REL Relative
IX Indexed, No Offset
IX1 Indexed, 8-Bit Offset
IX2 Indexed, 16-Bit Offset
IMD Immediate-Direct
DIX+ Direct-Indexed

SP1 Stack Pointer, 8-Bit Offset
SP2 Stack Pointer, 16-Bit Offset
IX+ Indexed, No Offset with Post Increment
IX1+ Indexed, 1-Byte Offset with Post Increment

*Pre-byte for stack pointer indexed instructions

Low Byte of Opcode in Hexadecimal

MSB LSB	0	5 BRSET0 3 DIR
0	High Byte of Opcode in Hexadecimal	Cycles Opcode Mnemonic Number of Bytes / Addressing Mode

7.4.2.5 LVI Reset

The low-voltage inhibit module (LVI) asserts its output to the SIM when the V_{DD} voltage falls to the LVI trip voltage V_{TRIP} . The LVI bit in the SIM reset status register (SRSR) is set, and the external reset pin (RSTB) is held low while the SIM counter counts out 4096 2OSCCLK cycles. Sixty-four 2OSCOU cycles later, the CPU and memories are released from reset to allow the reset vector sequence to occur. The SIM actively pulls down the (RSTB) pin for all internal reset sources.

7.5 SIM Counter

The SIM counter is used by the power-on reset module (POR) and in stop mode recovery to allow the oscillator time to stabilize before enabling the internal bus (IBUS) clocks. The SIM counter also serves as a prescaler for the computer operating properly module (COP). The SIM counter uses 12 stages for counting, followed by a 13th stage that triggers a reset of SIM counters and supplies the clock for the COP module. The SIM counter is clocked by the falling edge of 2OSCOU.

7.5.1 SIM Counter During Power-On Reset

The power-on reset module (POR) detects power applied to the MCU. At power-on, the POR circuit asserts the signal PORRST. Once the SIM is initialized, it enables the oscillator to drive the bus clock state machine.

7.5.2 SIM Counter During Stop Mode Recovery

The SIM counter also is used for stop mode recovery. The STOP instruction clears the SIM counter. After an interrupt, break, or reset, the SIM senses the state of the short stop recovery bit, SSREC, in the mask option register. If the SSREC bit is a logic one, then the stop recovery is reduced from the normal delay of 4096 2OSCOU cycles down to 32 2OSCOU cycles. This is ideal for applications using canned oscillators that do not require long start-up times from stop mode. External crystal applications should use the full stop recovery time, that is, with SSREC cleared in the configuration register (CONFIG).

protected from being cleared by properly initializing the break clear flag enable bit (BCFE) in the break flag control register (BFCR).

Protecting flags in break mode ensures that set flags will not be cleared while in break mode. This protection allows registers to be freely read and written during break mode without losing status flag information.

Setting the BCFE bit enables the clearing mechanisms. Once cleared in break mode, a flag remains cleared even when break mode is exited. Status flags with a two-step clearing mechanism — for example, a read of one register followed by the read or write of another — are protected, even when the first step is accomplished prior to entering break mode. Upon leaving break mode, execution of the second step will clear the flag as normal.

7.7 Low-Power Modes

Executing the WAIT or STOP instruction puts the MCU in a low-power-consumption mode for standby situations. The SIM holds the CPU in a non-clocked state. The operation of each of these modes is described below. Both STOP and WAIT clear the interrupt mask (I) in the condition code register, allowing interrupts to occur.

7.7.1 Wait Mode

In wait mode, the CPU clocks are inactive while the peripheral clocks continue to run. [Figure 7-15](#) shows the timing for wait mode entry.

A module that is active during wait mode can wake up the CPU with an interrupt if the interrupt is enabled. Stacking for the interrupt begins one cycle after the WAIT instruction during which the interrupt occurred. In wait mode, the CPU clocks are inactive. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

Wait mode can also be exited by a reset or break. A break interrupt during wait mode sets the SIM break stop/wait bit, SBSW, in the break

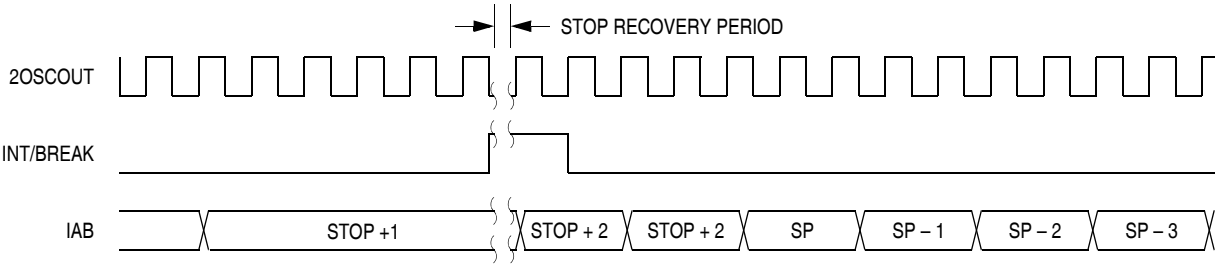


Figure 7-19. Stop Mode Recovery from Interrupt or Break

7.8 SIM Registers

The SIM has three memory mapped registers. [Table 7-4](#) shows the mapping of these registers.

Table 7-4. SIM Registers

Address	Register	Access Mode
\$FE00	BSR	User
\$FE01	RSR	User
\$FE03	BFCR	User

7.8.1 Break Status Register (BSR)

The break status register contains a flag to indicate that a break caused an exit from stop or wait mode.

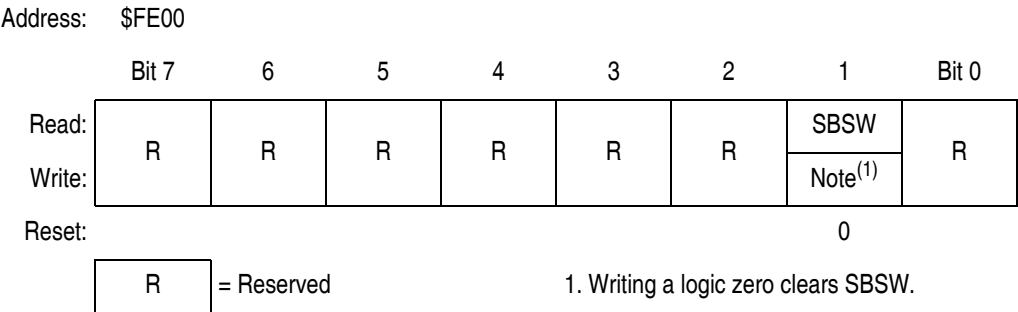


Figure 7-20. Break Status Register (BSR)

Setting MS0B links channels 0 and 1 and configures them for buffered PWM operation. The TIM channel 0 registers (TCH0H:TCH0L) initially control the buffered PWM output. TIM status control register 0 (TSCR0) controls and monitors the PWM signal from the linked channels. MS0B takes priority over MS0A.

Clearing the toggle-on-overflow bit, TOVx, inhibits output toggles on TIM overflows. Subsequent output compares try to force the output to a state it is already in and have no effect. The result is a 0% duty cycle output.

Setting the channel x maximum duty cycle bit (CHxMAX) and clearing the TOVx bit generates a 100% duty cycle output. (See [10.10.4 TIM Channel Status and Control Registers \(TSC0:TSC1\)](#).)

10.6 Interrupts

The following TIM sources can generate interrupt requests:

- TIM overflow flag (TOF) — The TOF bit is set when the TIM counter value rolls over to \$0000 after matching the value in the TIM counter modulo registers. The TIM overflow interrupt enable bit, TOIE, enables TIM overflow CPU interrupt requests. TOF and TOIE are in the TIM status and control register.
- TIM channel flags (CH1F:CH0F) — The CHxF bit is set when an input capture or output compare occurs on channel x. Channel x TIM CPU interrupt requests are controlled by the channel x interrupt enable bit, CHxIE. Channel x TIM CPU interrupt requests are enabled when CHxIE=1. CHxF and CHxIE are in the TIM channel x status and control register.

10.7 Wait Mode

The WAIT instruction puts the MCU in low-power-consumption standby mode.

The TIM remains active after the execution of a WAIT instruction. In wait mode the TIM registers are not accessible by the CPU. Any enabled CPU interrupt request from the TIM can bring the MCU out of wait mode.

11.3 Features

Features of the ADC module include:

- 12 channels with multiplexed input
- Linear successive approximation with monotonicity
- 8-bit resolution
- Single or continuous conversion
- Conversion complete flag or conversion complete interrupt
- Selectable ADC clock

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$003C	ADC Status and Control Register (ADSCR)	Read:	COCO	AIEN	ADCO	CH4	CH3	CH2	CH1	CH0
		Write:								
		Reset:	0	0	0	1	1	1	1	1
\$003D	ADC Data Register (ADR)	Read:	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0
		Write:								
		Reset:	Indeterminate after reset							
\$003E	ADC Input Clock Register (ADICLK)	Read:	ADIV2	ADIV1	ADIV0	0	0	0	0	0
		Write:								
		Reset:	0	0	0	0	0	0	0	0

Figure 11-1. ADC I/O Register Summary

11.4 Functional Description

Twelve ADC channels are available for sampling external sources at pins PTB0–PTB7 and PTD0–PTD3. An analog multiplexer allows the single ADC converter to select one of the 12 ADC channels as ADC voltage input (ADCVIN). ADCVIN is converted by the successive approximation register-based counters. The ADC resolution is 8 bits. When the conversion is completed, ADC puts the result in the ADC data register and sets a flag or generates an interrupt. [Figure 11-2](#) shows a block diagram of the ADC.

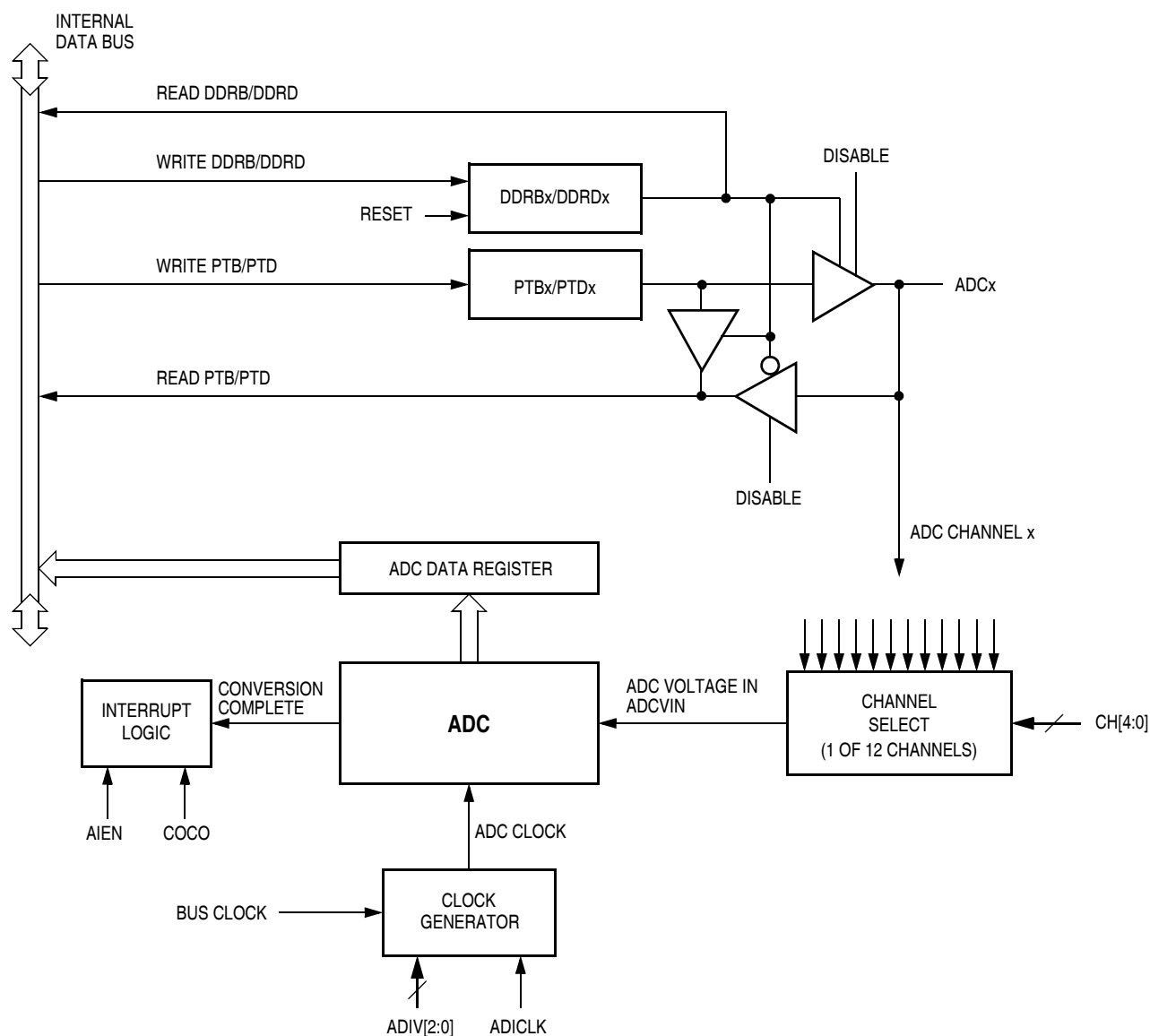


Figure 11-2. ADC Block Diagram

11.4.1 ADC Port I/O Pins

PTB0–PTB7 and PTD0–PTD3 are general-purpose I/O pins that are shared with the ADC channels. The channel select bits (ADC Status and Control register, \$003C), define which ADC channel/port pin will be used as the input signal. The ADC overrides the port I/O logic by forcing that pin as input to the ADC. The remaining ADC channels/port pins are controlled by the port I/O logic and can be used as general-purpose I/O.

Table 11-1. MUX Channel Select

CH4	CH3	CH2	CH1	CH0	ADC Channel	Input Select
0	0	0	0	0	ADC0	PTB0
0	0	0	0	1	ADC1	PTB1
0	0	0	1	0	ADC2	PTB2
0	0	0	1	1	ADC3	PTB3
0	0	1	0	0	ADC4	PTB4
0	0	1	0	1	ADC5	PTB5
0	0	1	1	0	ADC6	PTB6
0	0	1	1	1	ADC7	PTB7
0	1	0	0	0	ADC8	PTD3
0	1	0	0	1	ADC9	PTD2
0	1	0	1	0	ADC10	PTD1
0	1	0	1	1	ADC11	PTD0
0	1	1	0	0	—	Unused (see Note 1)
:	:	:	:	:		
1	1	0	1	0	—	Reserved
1	1	0	1	1		
1	1	1	0	0	—	Unused
1	1	1	0	1		V _{DDA} (see Note 2)
1	1	1	1	0		V _{SSA} (see Note 2)
1	1	1	1	1		ADC power off

NOTES:

1. If any unused channels are selected, the resulting ADC conversion will be unknown.
2. The voltage levels supplied from internal reference nodes as specified in the table are used to verify the operation of the ADC converter both in production test and for user applications.

11.8.2 ADC Data Register

One 8-bit result register is provided. This register is updated each time an ADC conversion completes.

Section 14. Keyboard Interrupt Module (KBI)

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14.2 Introduction

The keyboard interrupt module (KBI) provides seven independently maskable external interrupts which are accessible via PTA0–PTA6 pins.

14.3 Features

Features of the keyboard interrupt module include the following:

- Seven keyboard interrupt pins with separate keyboard interrupt enable bits and one keyboard interrupt mask
- Software configurable pull-up device if input pin is configured as input port bit
- Programmable edge-only or edge- and level- interrupt sensitivity
- Exit from low-power modes

18.6 5V DC Electrical Characteristics

Table 18-4. DC Electrical Characteristics (5V)

Characteristic ⁽¹⁾	Symbol	Min	Typ ⁽²⁾	Max	Unit
Output high voltage ($I_{LOAD} = -2.0\text{mA}$) PTA0–PTA6, PTB0–PTB7, PTD0–PTD7	V_{OH}	$V_{DD}-0.8$	—	—	V
Output low voltage ($I_{LOAD} = 1.6\text{mA}$) PTA6, PTB0–PTB7, PTD0, PTD1, PTD4, PTD5	V_{OL}	—	—	0.4	V
Output low voltage ($I_{LOAD} = 25\text{mA}$) PTD6, PTD7	V_{OL}	—	—	0.5	V
LED drives ($V_{OL} = 3\text{V}$) PTA0–PTA5, PTD2, PTD3, PTD6, PTD7	I_{OL}	10	19	25	mA
Input high voltage PTA0–PTA6, PTB0–PTB7, PTD0–PTD7, $\overline{RST}$, $\overline{IRQ1}$, OSC1	V_{IH}	$0.7 \times V_{DD}$	—	V_{DD}	V
Input low voltage PTA0–PTA6, PTB0–PTB7, PTD0–PTD7, $\overline{RST}$, $\overline{IRQ1}$, OSC1	V_{IL}	V_{SS}	—	$0.3 \times V_{DD}$	V
V_{DD} supply current Run, $f_{OP} = 4\text{MHz}$ ⁽³⁾ Wait (MC68HRC908xxx) ⁽⁴⁾ Wait (MC68HC908xxx) ⁽⁴⁾ Stop ⁽⁵⁾ -40°C to 85°C	I_{DD}	— — — —	7 1 5 1	10 1.5 5.5 5	mA mA mA μA
Digital I/O ports Hi-Z leakage current	I_{IL}	—	—	± 10	μA
Input current	I_{IN}	—	—	± 1	μA
Capacitance Ports (as input or output)	C_{OUT} C_{IN}	— —	— —	12 8	pF
POR rearm voltage ⁽⁶⁾	V_{POR}	0	—	100	mV
POR rise time ramp rate ⁽⁷⁾	R_{POR}	0.035	—	—	V/ms
Monitor mode entry voltage	$V_{DD}+V_{HI}$	$1.5 \times V_{DD}$	—	8.5	V
Pullup resistors ⁽⁸⁾ PTD6, PTD7 $\overline{RST}$, $\overline{IRQ1}$, PTA0–PTA6	R_{PU1} R_{PU2}	1.8 16	3.3 26	4.8 36	k Ω k Ω
LVI reset voltage	V_{LVR5}	3.6	4.0	4.4	V

18.14 Memory Characteristics

Table 18-11. Memory Characteristics

Characteristic	Symbol	Min	Max	Unit
RAM data retention voltage	V_{RDR}	1.3	—	V
FLASH program bus clock frequency	—	1	—	MHz
FLASH read bus clock frequency	$f_{Read}^{(1)}$	32k	8M	Hz
FLASH page erase time	$t_{Erase}^{(2)}$	1	—	ms
FLASH mass erase time	$t_{MErase}^{(3)}$	4	—	ms
FLASH PGM/ERASE to HVEN set up time	t_{nvs}	10	—	μ s
FLASH high-voltage hold time	t_{nvh}	5	—	μ s
FLASH high-voltage hold time (mass erase)	t_{nvhl}	100	—	μ s
FLASH program hold time	t_{pgs}	5	—	μ s
FLASH program time	t_{PROG}	30	40	μ s
FLASH return to read time	$t_{rcv}^{(4)}$	1	—	μ s
FLASH cumulative program hv period	$t_{HV}^{(5)}$	—	4	ms
FLASH row erase endurance ⁽⁶⁾	—	10k	—	cycles
FLASH row program endurance ⁽⁷⁾	—	10k	—	cycles
FLASH data retention time ⁽⁸⁾	—	10	—	years

NOTES:

- f_{Read} is defined as the frequency range for which the FLASH memory can be read.
- If the page erase time is longer than t_{Erase} (Min), there is no erase-disturb, but it reduces the endurance of the FLASH memory.
- If the mass erase time is longer than t_{MErase} (Min), there is no erase-disturb, but it reduces the endurance of the FLASH memory.
- t_{rcv} is defined as the time it needs before the FLASH can be read after turning off the high voltage charge pump, by clearing HVEN to logic 0.
- t_{HV} is defined as the cumulative high voltage programming time to the same row before next erase.
 t_{HV} must satisfy this condition: $t_{nvs} + t_{nvh} + t_{pgs} + (t_{PROG} \times 32) \leq t_{HV} \text{ max.}$
- The minimum row endurance value specifies each row of the FLASH memory is guaranteed to work for at least this many erase / program cycles.
- The minimum row endurance value specifies each row of the FLASH memory is guaranteed to work for at least this many erase / program cycles.
- The FLASH is guaranteed to retain data over the entire operating temperature range for at least the minimum time specified.